

ADHESIVE SHEET FOR LASER DICING AND METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE

ABSTRACT

An adhesive sheet for laser dicing is provided that is capable of, in laser dicing by irradiation with laser light through the adhesive sheet, suppressing laser light scattering in the adhesive sheet while allowing easy chip division by expanding the adhesive sheet and enables inhibition of dust attachment during chip division for chip production in high yields. The present invention provides an adhesive sheet for laser dicing, including a substrate film having a back layer containing a friction reducing agent and an antistatic agent on one surface and having an adhesive layer on another surface, wherein the back layer has a surface with arithmetic mean roughness Ra of 0.1 μm or less, the sheet has a tensile modulus of elasticity at 23°C from 50 to 200 MPa, and the sheet has a parallel transmittance of 85% or more in a wavelength range from 400 to 1400 nm.

[Figure 1]